



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21B106KOQNNNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 10 µF, 16V, ±10%, X7R, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>B</u> <u>106</u> <u>K</u> <u>O</u> <u>Q</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Serie	s Samsun	Samsung Multi-layer Ceramic Capacitor							
② Size	0805 ((inch code) L: 2.	.0	± 0.15	mm	W:	1.25	± 0.15	mm
3 Diele	ctric X7R	,	(8)	Inner ele	otrodo		Ni		
_		·	•				-		
4 Capa	citance 10 ,	μ F		Termina	tion		Cu		
⑤ Capa	citance ±10 °	%		Plating			Sn 100)%	(Pb Free)
tolera	ance	(9	Product			Norma	l	
6 Rate	d Voltage 16 \	V	10	Special			Reserv	ed for f	uture use
7 Thick	ness 1.25 :	± 0.15 mm	11)	Packagi	ng		Embos	sed Ty	pe, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1kHz±10% 0.5±0.1Vrms				
Tan δ (DF)	0.1 max.]				
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X7R					
Characteristics	(From -55 ℃ to 125 ℃, Capacitance change should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120°C for 10~30sec.)				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition					
Vibration Test	Capacitance change : within ±5%	Amplitude: 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change : within ±12.5%	With rated voltage					
Resistance	Tan δ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR : 12.5MΩ·μF or Over						
High Temperature	Capacitance change: within ±12.5%	With 150% of the rated voltage					
Resistance	Tan δ: 0.125 max	Max. operating temperature					
	IR : 25MΩ·μF or Over						
		1000+48/-0hrs					
Temperature	Capacitance change : within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C					
		→ Max. operating temperature → 25°C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.